

[54] HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS

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[\*\*] Term: 14 Years

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[30] Foreign Application Priority Data

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[52] U.S. Cl. .... D13/23

[58] Field of Search ..... D13/23; 165/80 R, 80 A, 165/80 B, 80 D; 357/81; 174/16 HS

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[57] CLAIM

The ornamental design for heat releasing plate for mounting semiconductor components, as shown and described.

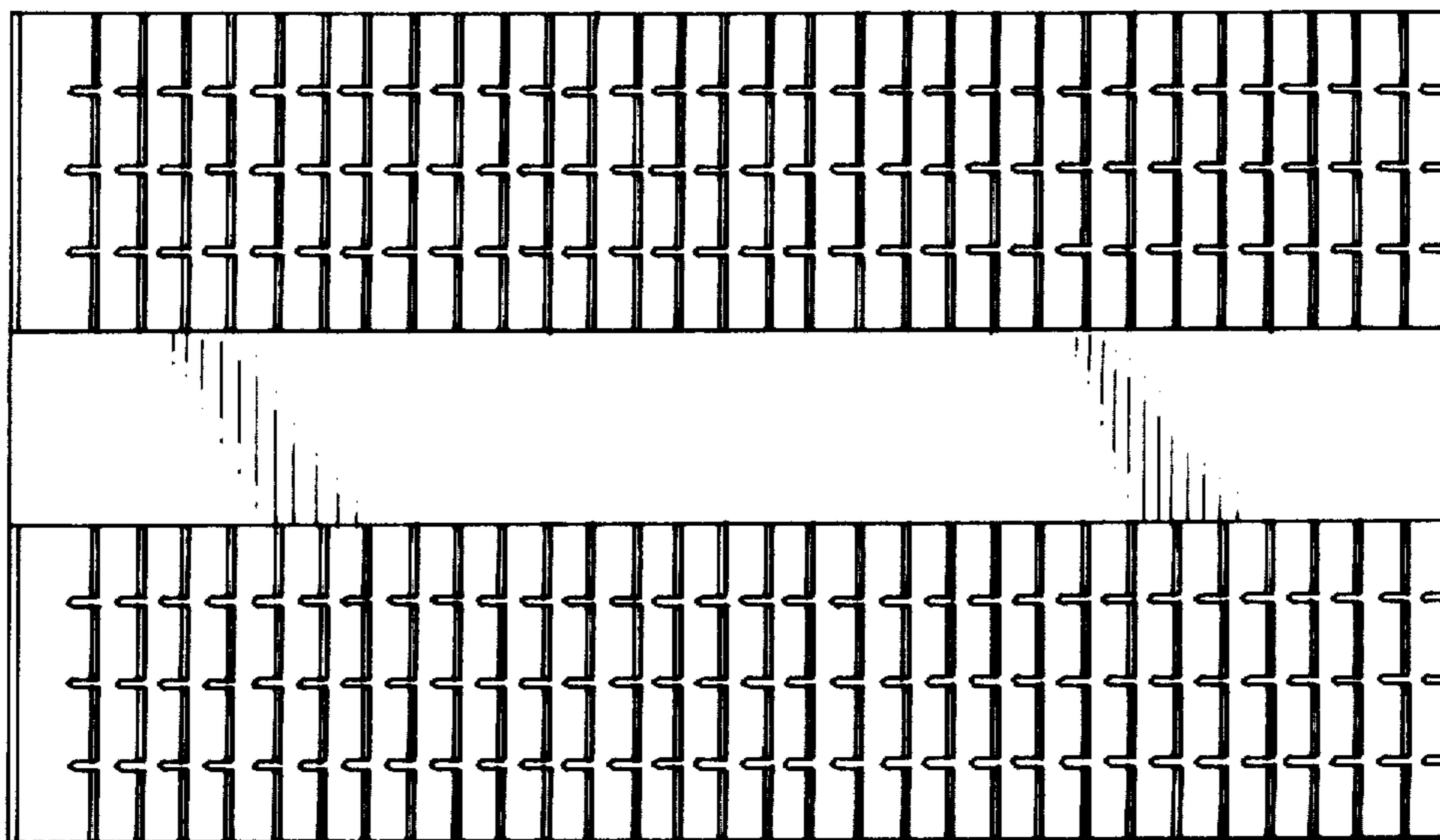
DESCRIPTION

FIG. 1 is a front view of the heat releasing plate for mounting semiconductor components showing the new design;

FIG. 2 is a plan view thereof;

FIG. 3 is a right side view thereof; and

FIG. 4 is a sectional view taken on line 4-4 of FIG. 1.



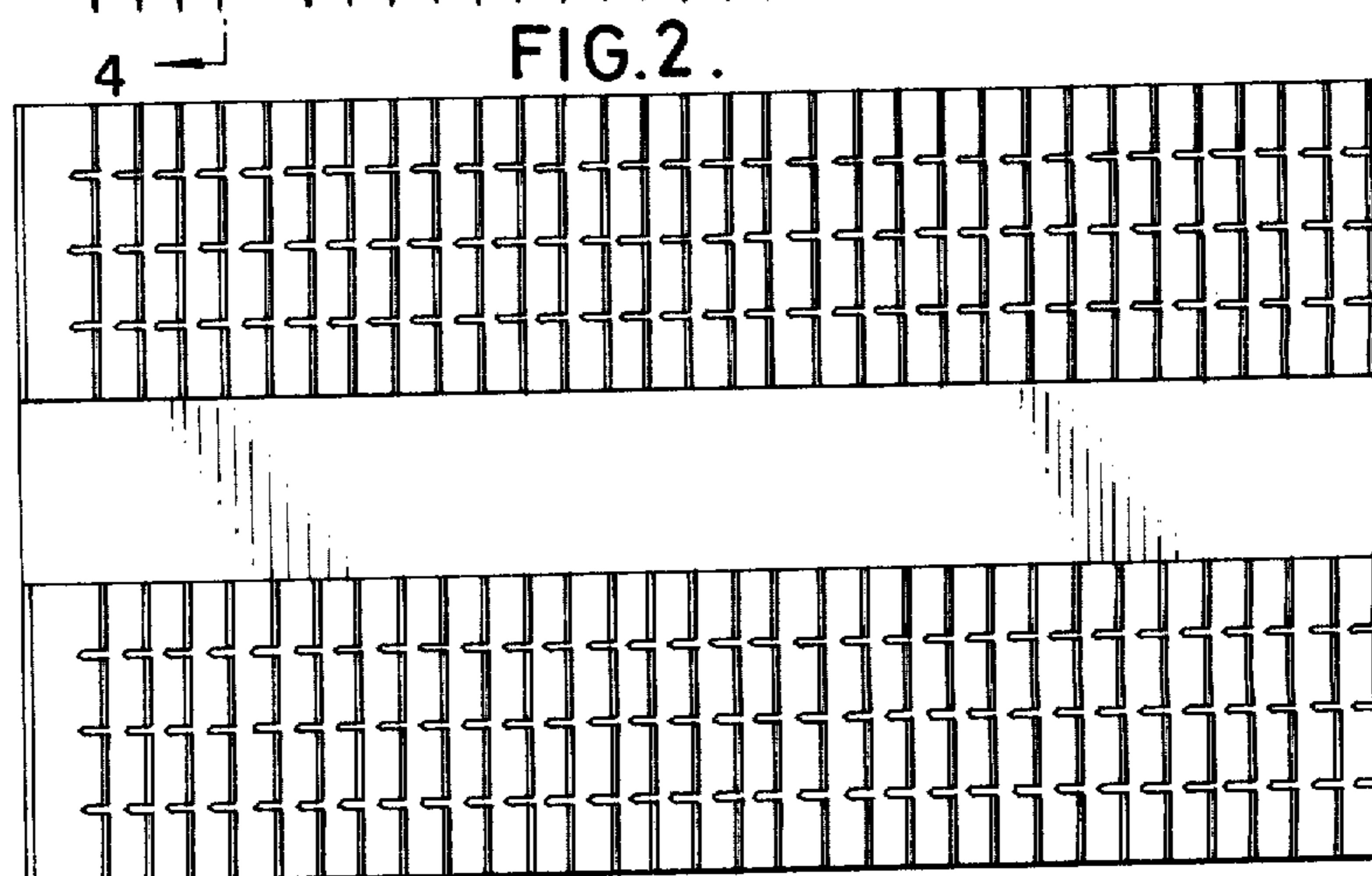
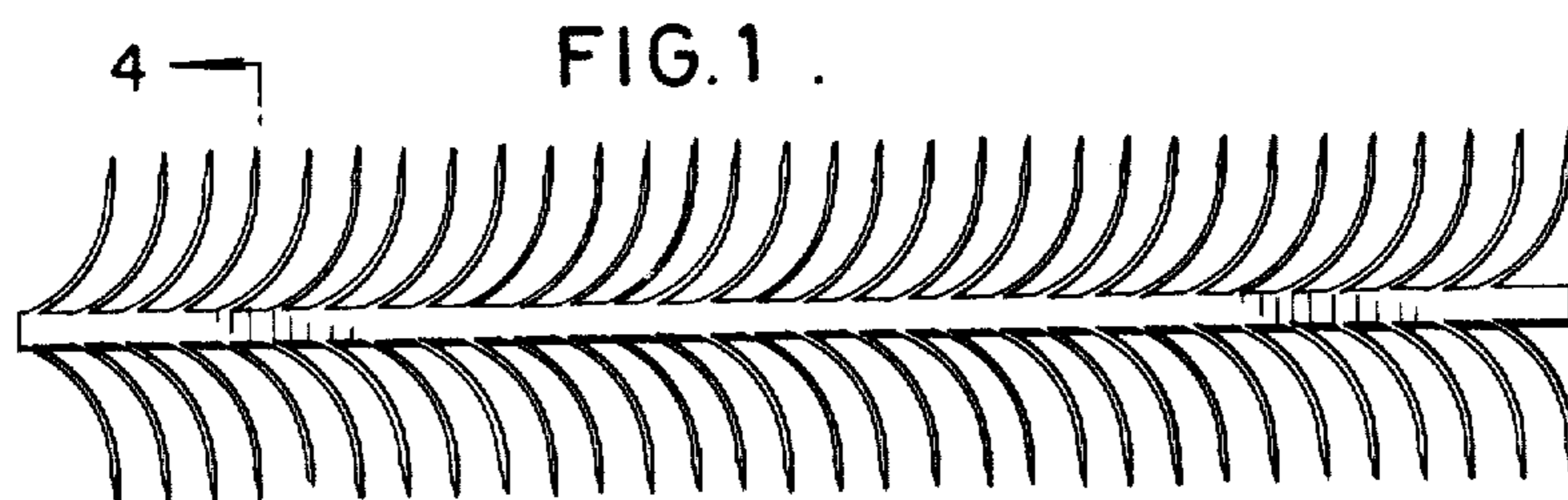


FIG. 3 .

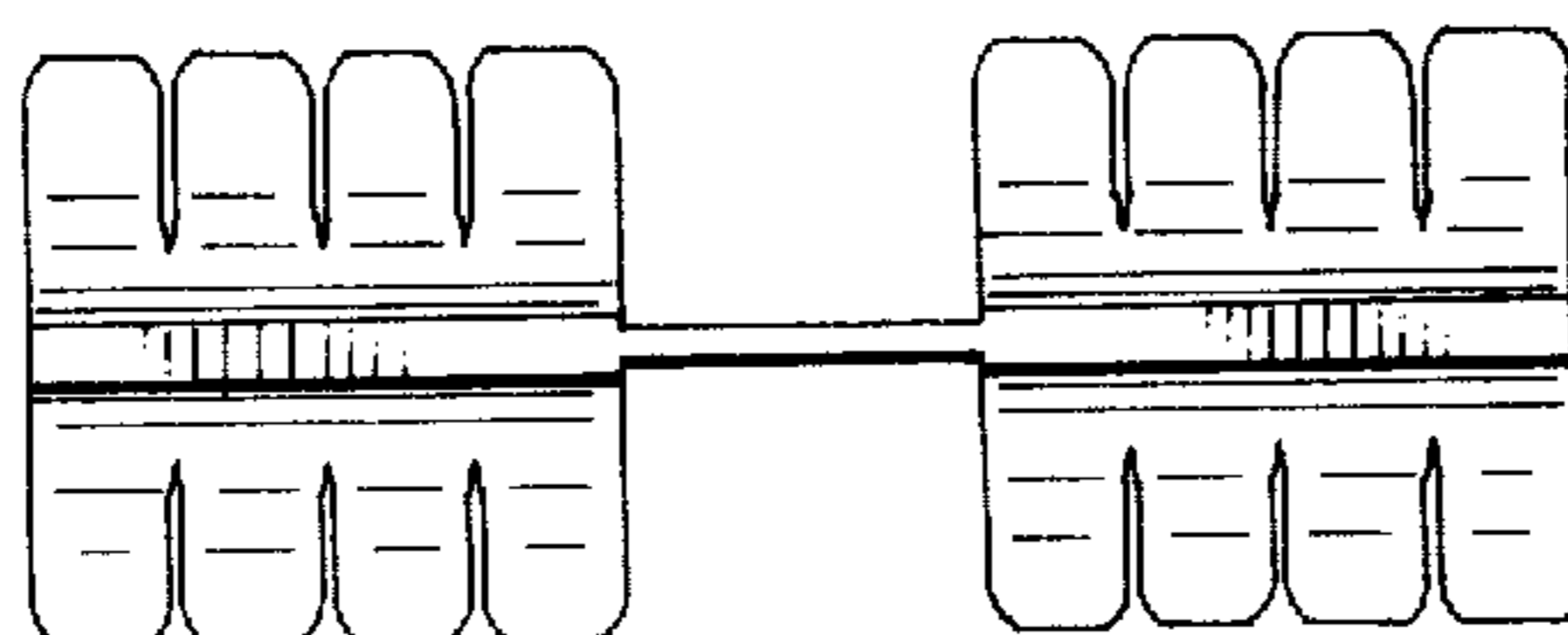


FIG. 4 .

